

# BSS64LT1

## Driver Transistor

### NPN Silicon

#### Features

- Pb-Free Package is Available

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	$V_{CEO}$	80	Vdc
Collector–Base Voltage	$V_{CBO}$	120	Vdc
Emitter–Base Voltage	$V_{EBO}$	5.0	Vdc
Collector Current – Continuous	$I_C$	100	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	–55 to +150	$^\circ\text{C}$

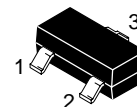
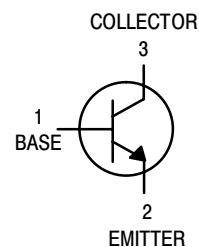
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- FR–5 = 1.0 x 0.75 x 0.062 in.
- Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



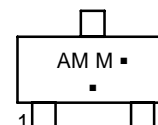
ON Semiconductor®

<http://onsemi.com>



SOT–23 (TO–236)  
CASE 318  
STYLE 6

#### MARKING DIAGRAM



AM = Device Code  
M = Date Code\*  
■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
BSS64LT1	SOT–23	3,000 / Tape & Reel
BSS64LT1G	SOT–23 (Pb–Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# BSS64LT1

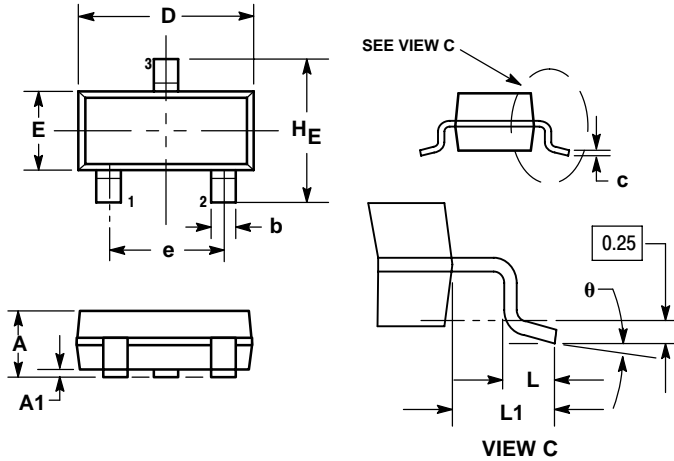
## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector–Emitter Breakdown Voltage ( $I_C = 4.0\text{ mAdc}$ )	$V_{(BR)CEO}$	80	–	Vdc
Collector–Base Breakdown Voltage ( $I_C = 100\text{ }\mu\text{Adc}$ )	$V_{(BR)CBO}$	120	–	Vdc
Emitter–Base Breakdown Voltage ( $I_E = 100\text{ }\mu\text{Adc}$ )	$V_{(BR)EBO}$	5.0	–	Vdc
Collector Cutoff Current ( $V_{CE} = 90\text{ Vdc}$ ) ( $T_A = 150^\circ\text{C}$ )	$I_{CBO}$	– –	0.1 500	$\mu\text{Adc}$
Emitter Cutoff Current ( $V_{EB} = 4.0\text{ Vdc}$ )	$I_{EBO}$	–	200	nAdc
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $V_{CE} = 1.0\text{ Vdc}$ , $I_C = 10\text{ mAdc}$ )	$H_{FE}$	20	–	–
Collector–Emitter Saturation Voltage ( $I_C = 4.0\text{ mAdc}$ , $I_B = 400\text{ }\mu\text{Adc}$ ) ( $I_C = 50\text{ mAdc}$ , $I_B = 15\text{ mAdc}$ )	$V_{CE(sat)}$	– –	0.15 0.2	Vdc
Forward Base–Emitter Voltage	$V_{BE(sat)}$	–	–	–
<b>SMALL–SIGNAL CHARACTERISTICS</b>				
Current–Gain – Bandwidth Product ( $I_C = 4.0\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 20\text{ MHz}$ )	$f_T$	60	–	MHz
Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $f = 1.0\text{ MHz}$ )	$C_{ob}$	–	20	pF

# BSS64LT1

## PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AN



NOTES:

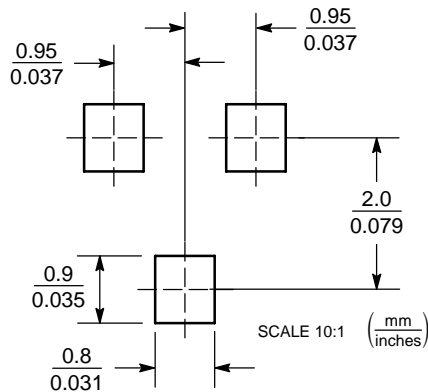
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

1. BASE
2. EMITTER
3. COLLECTOR

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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